



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

Scott M. Zimmerman, et al.

Docket: OM-1670

Serial Number: 09/808,752

Group Art Unit: 4335

Filed: March 15, 2001

Examiner: Anita K. Alanko

For: POLYIMIDE ADHESION ENHANCEMENT TO POLYIMIDE FILM

AMENDMENT

Commissioner for Patents

P.O. BOX 1450

Alexandria, Virginia 22313-1450

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In response to the Office Action mailed July 31, 2003, please amend the above identified patent application as follows:

In the claims:

1. (Withdrawn and Currently Amended) A process for forming a printed circuit board composite comprising:

- a) etching at least one surface of a polyimide substrate;
- b) coating a ~~first~~ polyimide film onto a surface of a metal foil which polyimide film contains from about 5% to about 80% by weight of the film of a filler; and
- c) laminating the ~~first~~ polyimide film onto the substrate by:
 - i.) laminating the ~~first~~ polyimide film directly onto at least one etched surface of the substrate, or
 - ii.) laminating the ~~first~~ polyimide film onto at least one etched surface of the substrate via an intermediate ~~second~~ polymeric film; and